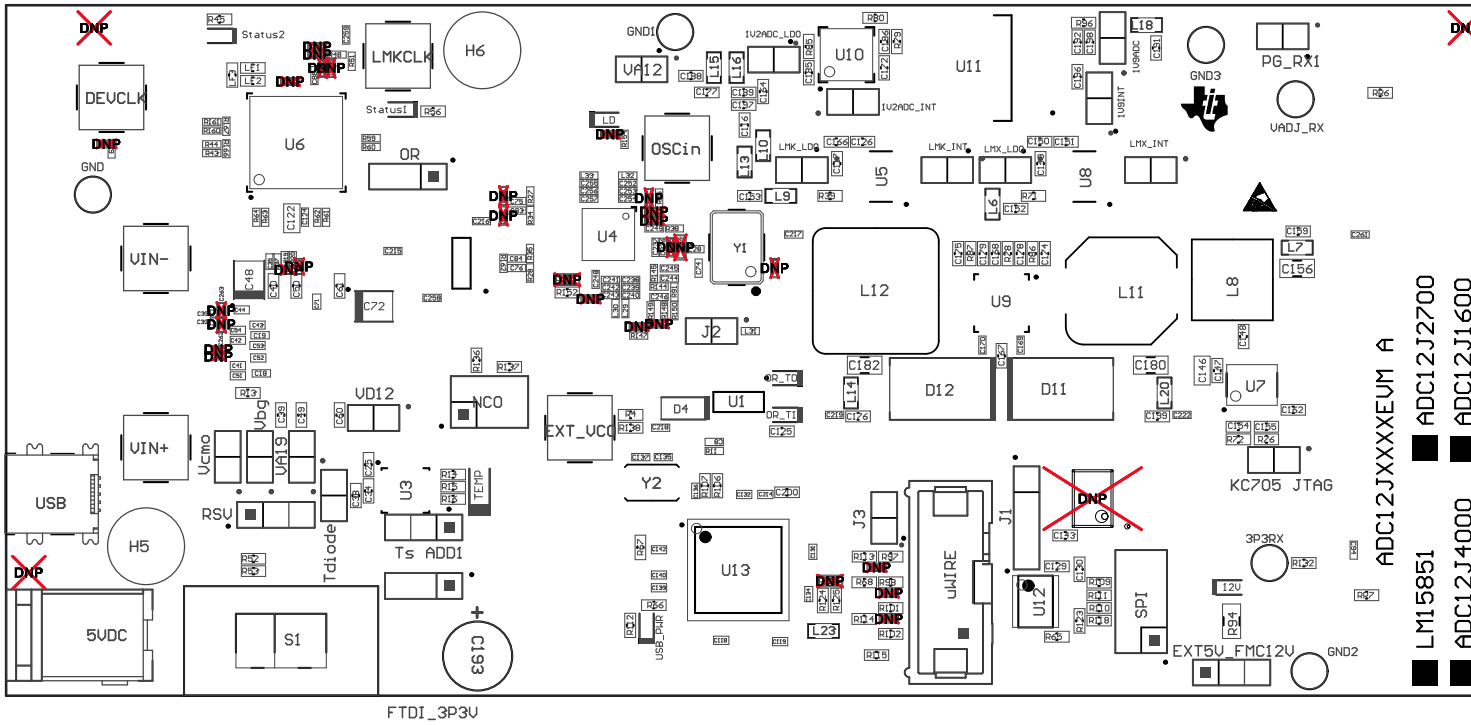


- Z21 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per Table 1
- Z22 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
- Z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- Z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.



- ADC12JXXXXEVM A
- LM15851
- ADC12J2700
- ADC12J4000
- ADC12J1600

TABLE 1

Variant	Label text
001	LM15851EVM
002	ADC12J4000EVM
003	ADC12J2700EVM
004	ADC12J1600EVM

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS  
 ASSEMBLY VARIANT: 002\_ADC12J4000EVM

PCB VIEWED FROM TOP SIDE	BOARD #: 600847	REV: A	SUN REV: Not In VersionControl
IGNORE -> Top Overlay			
PLOT NAME = Top Assembly Drawing	GENERATED : 9/29/2014 10:16:06 AM	TEXAS INSTRUMENTS	



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